REMARKS

Claims 1-4, 6-13, 15-18 and 31-34 are pending in this application. Claims 2-4, 6, 11-13, 15 and 31-34 are withdrawn. By this Amendment, claims 5, 14 and 19-30 are canceled, and claims 1 and 10 are amended for clarity. No new matter is added by this Amendment. Support for the features added to claims 1 and 10 is found at, for example, page 9, lines 6-7 of the present specification, and original claims 5 and 14. Applicant reserves the right to file one or more divisional applications to pursue non-elected claims 19-30.

I. Rejoinder

Non-elected claims 19-30 are herein canceled. However, each non-elected claim 2-4, 6, 31 and 33 depend from elected claim 1, and each non-elected claim 11-13, 15, 32 and 34 depend from elected claim 10. Accordingly, upon allowance of claims 1 and 10, claims 2-4, 6, 11-13, 15 and 31-34 should be rejoined with the application and similarly allowed.

II. Rejection Under 35 U.S.C. §103(a)

Claims 1, 5, 7-10, 14 and 16-18 are rejected under 35 U.S.C. §103(a) over U.S. Patent No. 6,621,172 (Nakayama) in combination with U.S. Patent No. 6,638,781 (Hirakata). This rejection is respectfully traversed.

Claims 1 and 10 are amended to recite that the insulating section is formed so that part of the insulating section under the interconnect does not overlay the first surface, and that the interconnect is formed on the passivation film. These features are not disclosed or suggested in the cited references.

More specifically, Hirakata is relied upon merely for disclosing an insulating resin; and Nakayama clearly fails to disclose a chip component having a passivation film formed on the first surface, and an interconnect which is formed to extend from above the electrode, over the insulating section, on the passivation film, and above the interconnect pattern, the

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insulating section being formed so that part of the insulating section under the interconnect does not overlay the first surface, as recited in claims 1 and 10.

Accordingly, Nakayama in combination with Hirakata fail to render obvious the subject matter of claims 1 and 10, as well as the claims depending therefrom.

Withdrawal of the rejection is requested.

III. Conclusion

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance of the pending claims are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,

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